OptiMOS® Buck converter series

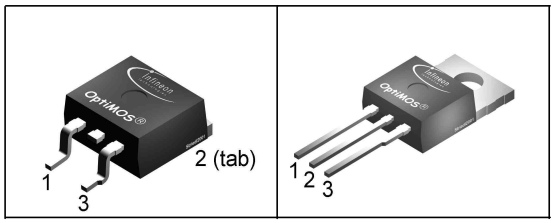
Feature

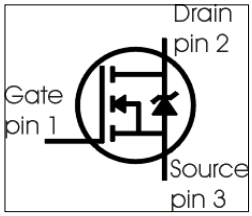
- N-Channel
- Logic Level
- Low On-Resistance $R_{DS(on)}$
- Excellent Gate Charge x $R_{DS(on)}$ product (FOM)
- Superior thermal resistance
- 175°C operating temperature
- Avalanche rated
- d*v*/d*t* rated
- Ideal for fast switching buck converters

Product Summary

V_{DS}	30	V
$R_{DS(on)}$ max. SMD version	8.9	mΩ
I_D	73	A

P- TO263 -3-2 P- TO220 -3-1





Type	Package	Ordering Code	Marking
IPP10N03L	P- TO220 -3-1	Q67042-S4040	10N03L
IPB10N03L	P- TO263 -3-2	Q67040-S4346	10N03L

Maximum Ratings, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current[1)] T_C=25°C	I_D	 73 63	A
Pulsed drain current T_C=25°C	$I_{D\ puls}$	292	
Avalanche energy, single pulse I_D=30A, V_{DD}=25V, R_{GS}=25Ω	E_{AS}	25	mJ
Repetitive avalanche energy, limited by T_{jmax}[2)]	E_{AR}	10	
Reverse diode d*v*/d*t* I_S=73A, V_{DS}=24, d*i*/d*t*=200A/µs, T_{jmax}=175°C	d*v*/d*t*	6	kV/µs
Gate source voltage	V_{GS}	±20	V
Power dissipation T_C=25°C	P_{tot}	107	W
Operating and storage temperature	T_j, T_{stg}	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	0.9	1.4	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	62	
@ 6 cm^2 cooling area [3]		-	-	40	

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage V_{GS}=0V, I_D=1mA	$V_{(BR)DSS}$	30	-	-	V
Gate threshold voltage, V_{GS} = V_{DS} I_D=60µA	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current	I_{DSS}				µA
V_{DS}=30V, V_{GS}=0V, T_j=25°C		-	0.01	1	
V_{DS}=30V, V_{GS}=0V, T_j=175°C		-	10	100	
Gate-source leakage current V_{GS}=20V, V_{DS}=0V	I_{GSS}	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$				mΩ
V_{GS}=4.5V, I_D=36A		-	9.9	13.4	
V_{GS}=4.5V, I_D=36A, SMD version		-	9.5	13.1	
Drain-source on-state resistance[4]	$R_{DS(on)}$				
V_{GS}=10V, I_D=36A		-	6.8	9.2	
V_{GS}=10V, I_D=36A, SMD version		-	6.5	8.9	

[1] Current limited by bondwire ; with an R_{thJC} = 1.4K/W the chip is able to carry I_D= 88A at 25°C, for detailed information see app.-note ANPS071E available at *www.infineon.com/optimos*

[2] Defined by design. Not subject to production test.

[3] Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air.

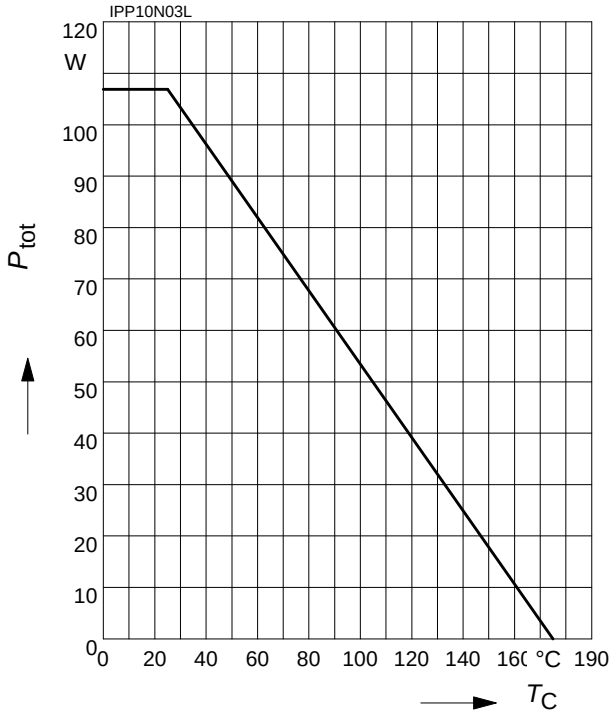
[4] Diagrams are related to straight lead versions

Electrical Characteristics

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Transconductance	g_{fs}	$V_{DS}\geq 2*I_D*R_{DS(on)max}$, I_D=63A	32	63	-	S
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=25V, f=1MHz	-	1290	1710	pF
Output capacitance	C_{oss}		-	500	670	
Reverse transfer capacitance	C_{rss}		-	130	190	
Gate resistance	R_G		-	1.4	-	Ω
Turn-on delay time	$t_{d(on)}$	V_{DD}=15V, V_{GS}=10V, I_D=18A, R_G=4.7Ω	-	7.7	11.6	ns
Rise time	t_r		-	20	30	
Turn-off delay time	$t_{d(off)}$		-	31.5	47.3	
Fall time	t_f		-	19	28.5	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=15V, I_D=36A	-	4	5	nC
Gate to drain charge	Q_{gd}		-	10.6	13.3	
Gate charge total	Q_g	V_{DD}=15V, I_D=36A, V_{GS}=0 to 5V	-	19	23.8	
Output charge	Q_{oss}	V_{DS}=15V, I_D=36A, V_{GS}=0V	-	18.2	22.8	nC
Gate plateau voltage	$V_{(plateau)}$	V_{DD}=15V, I_D=36A	-	3.6	-	V
Reverse Diode						
Inverse diode continuous forward current	I_S	T_C=25°C	-	-	73	A
Inv. diode direct current, pulsed	I_{SM}		-	-	292	
Inverse diode forward voltage	V_{SD}	V_{GS}=0V, I_F=73A	-	0.96	1.28	V
Reverse recovery time	t_{rr}	V_R=15V, I_F=I_S, di_F/dt=100A/µs	-	32.9	41.2	ns
Reverse recovery charge	Q_{rr}		-	33	41	nC

1 Power dissipation

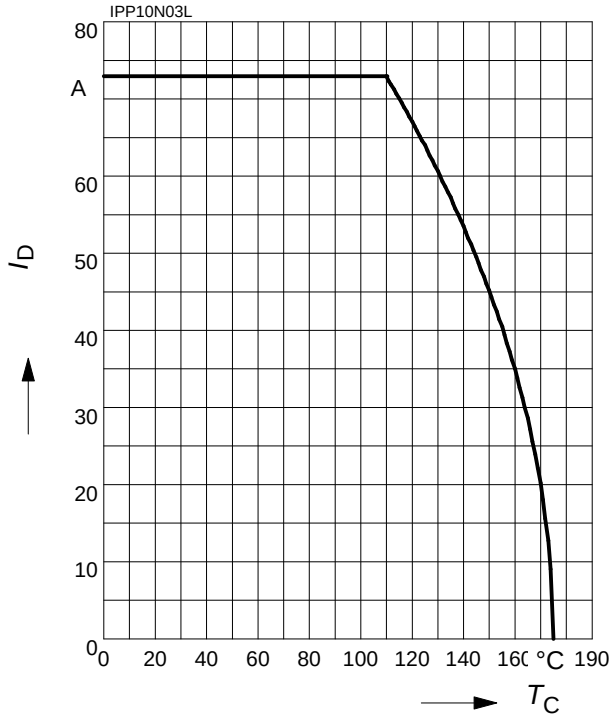
$P_{tot} = f(T_C)$



2 Drain current

$I_D = f(T_C)$

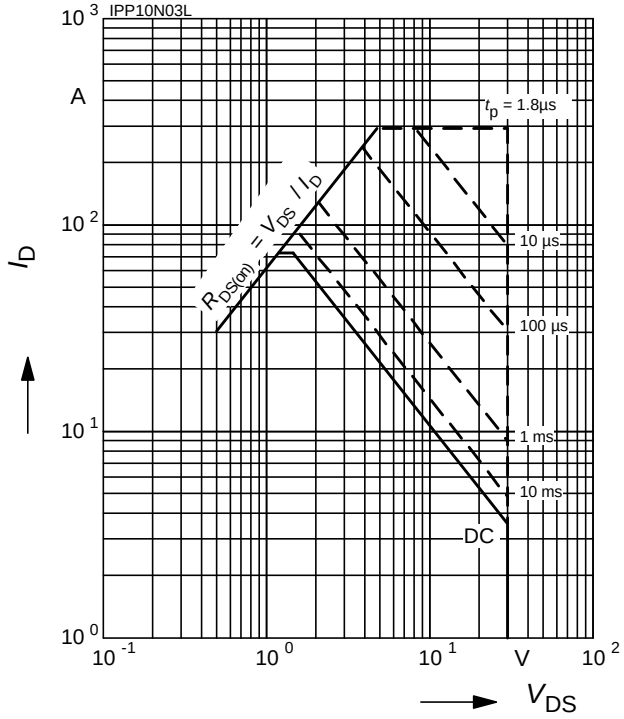
parameter: $V_{GS} \geq 10$ V



3 Safe operating area

$I_D = f(V_{DS})$

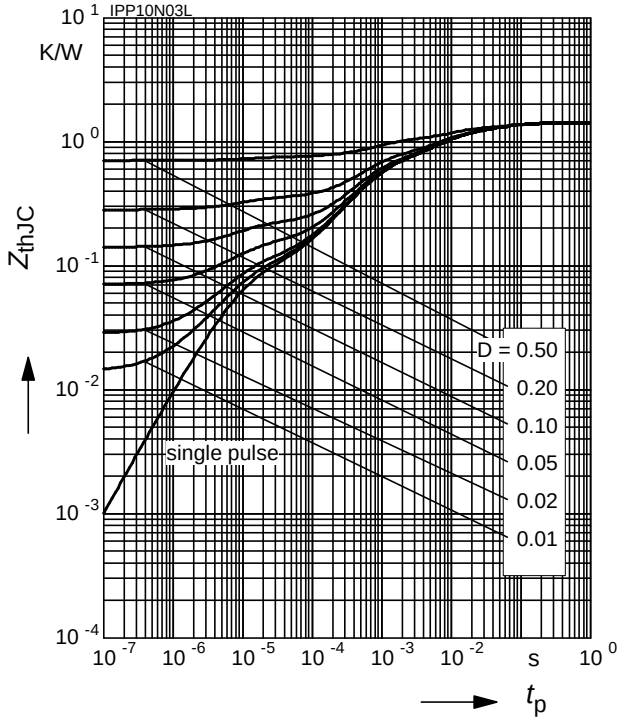
parameter : $D = 0$, $T_C = 25$ °C



4 Max. transient thermal impedance

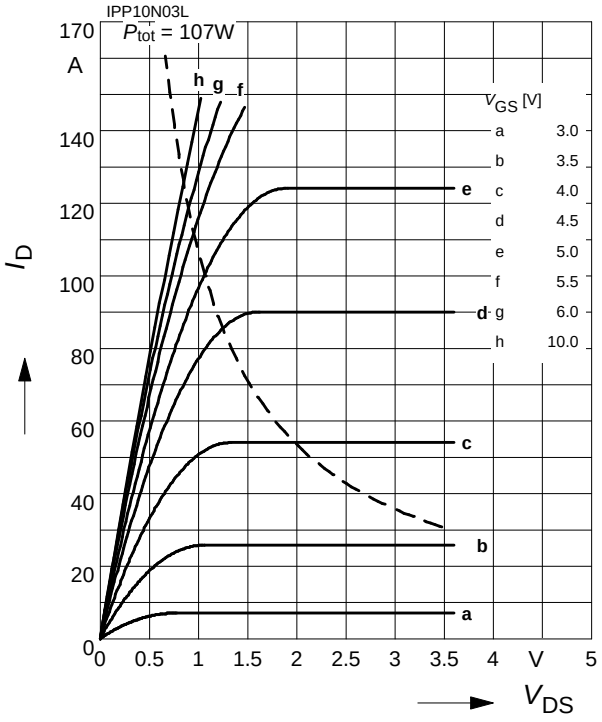
$Z_{thJC} = f(t_p)$

parameter : $D = t_p/T$



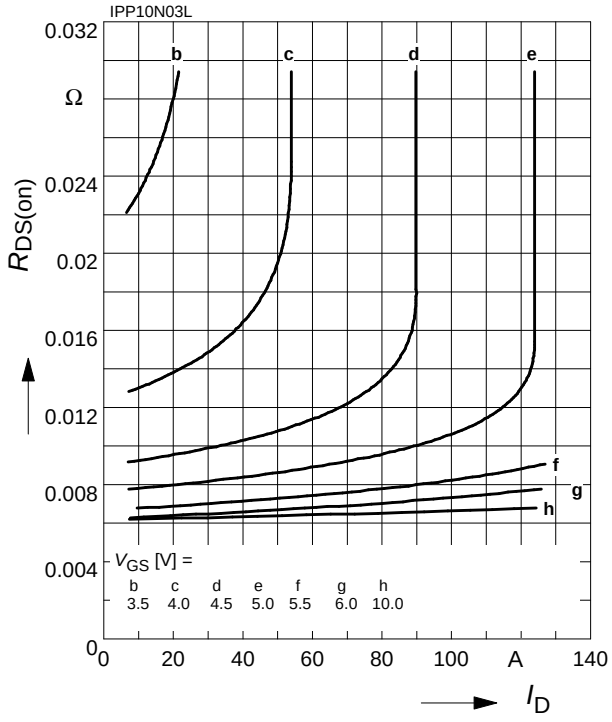
5 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=25°C
parameter: t_p = 80 µs



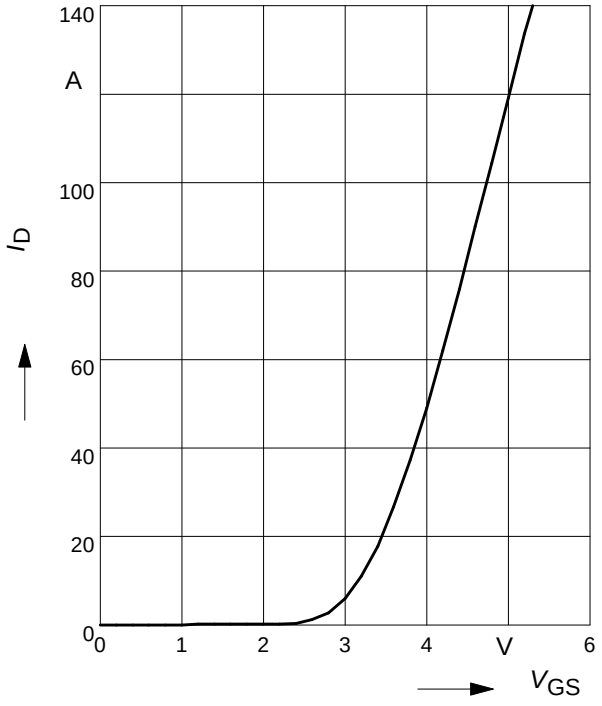
6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$
parameter: V_{GS}



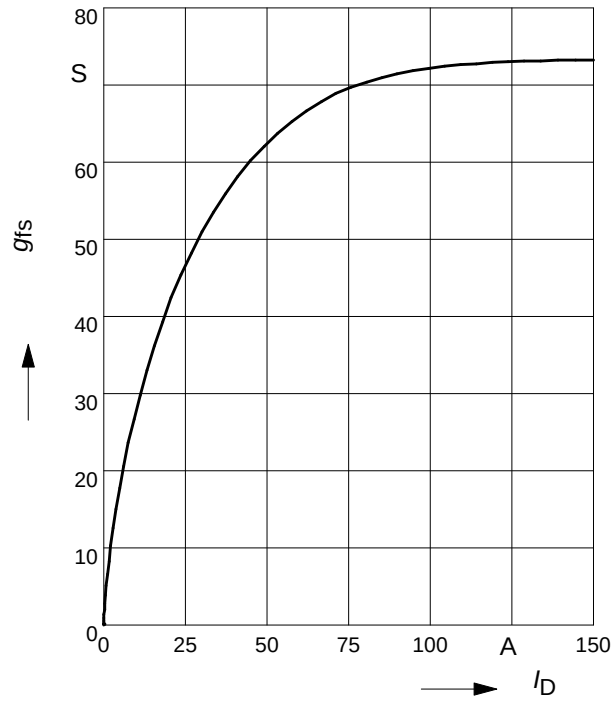
7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$
parameter: t_p = 80 µs



8 Typ. forward transconductance

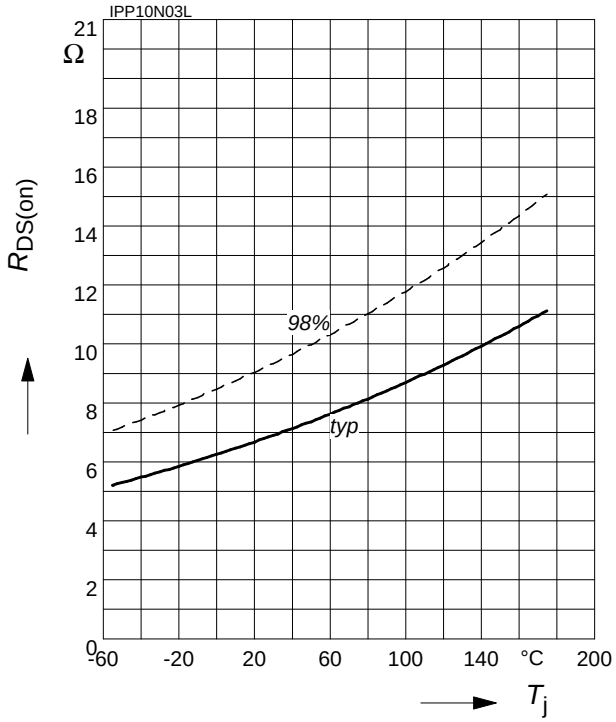
$g_{fs} = f(I_D)$; T_j=25°C
parameter: g_{fs}



9 Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$

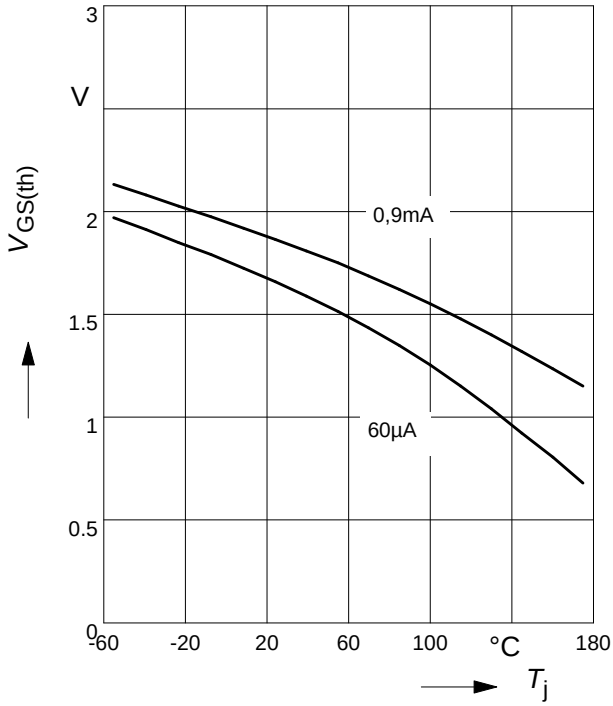
parameter : I_D = 36 A, V_{GS} = 10 V



10 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$

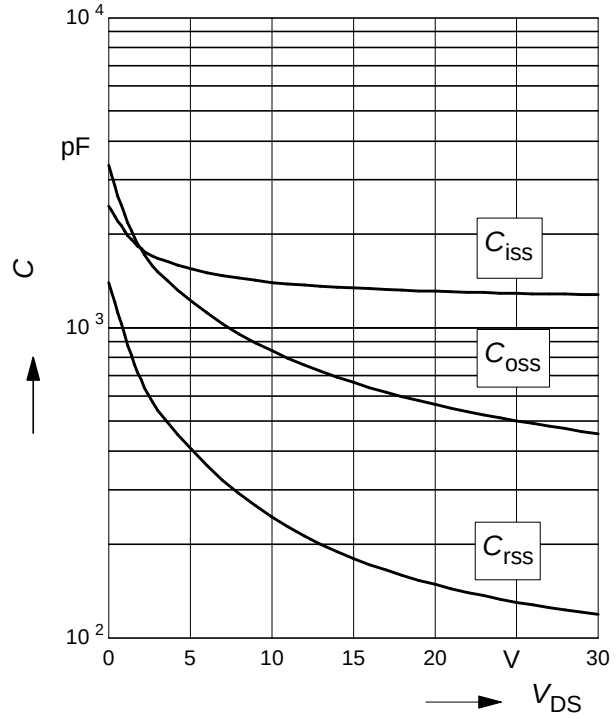
parameter: $V_{GS} = V_{DS}$



11 Typ. capacitances

$C = f(V_{DS})$

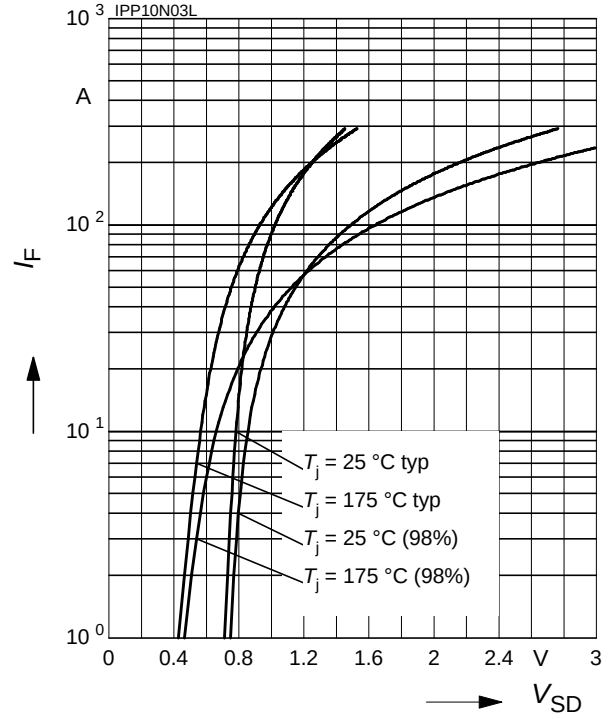
parameter: V_{GS}=0V, f=1 MHz



12 Forward character. of reverse diode

$I_F = f(V_{SD})$

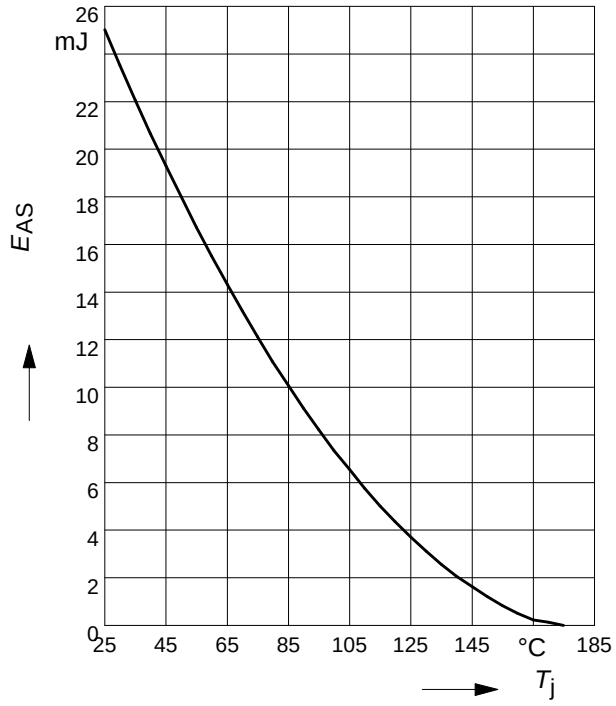
parameter: T_j , tp = 80 µs



13 Typ. avalanche energy

$E_{AS} = f(T_j)$

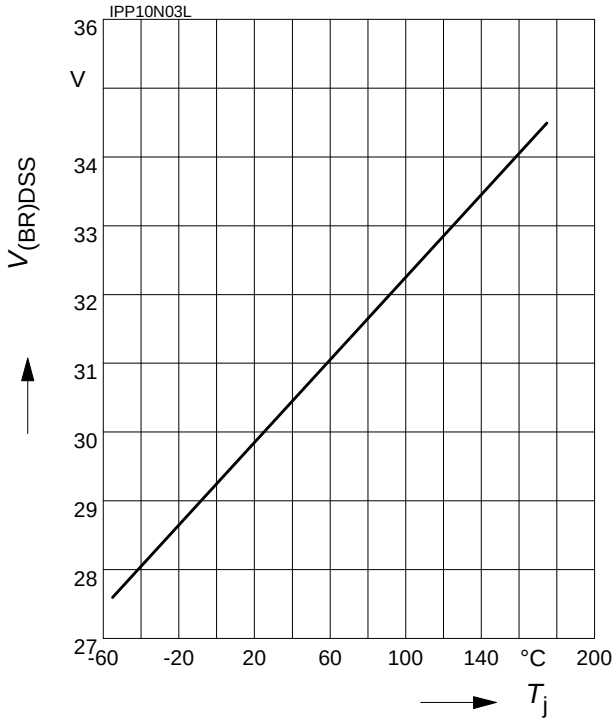
par.: I_D = 30 A, V_{DD} = 25 V, R_{GS} = 25 Ω



15 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$

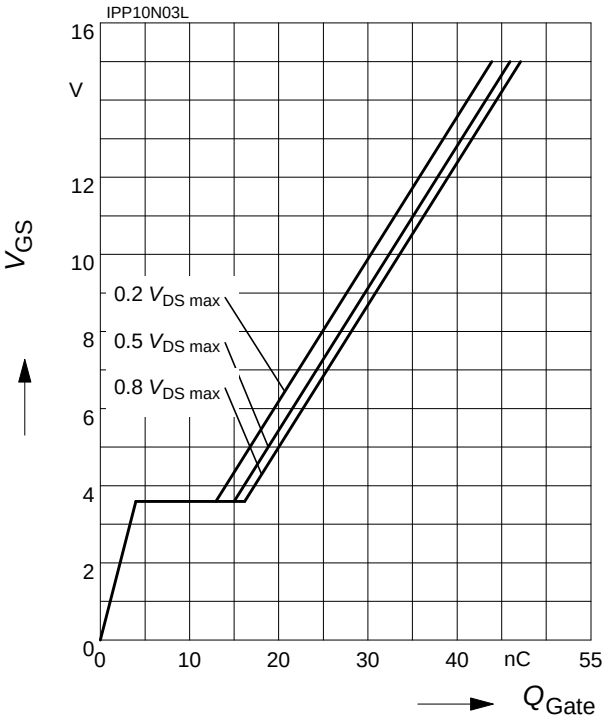
parameter: I_D=10 mA



14 Typ. gate charge

$V_{GS} = f(Q_{Gate})$

parameter: I_D = 36 A pulsed



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